### SN65LBC184, SN75LBC184 DIFFERENTIAL TRANSCEIVER WITH TRANSIENT VOLTAGE SUPPRESSION SLLS236G – OCTOBER 1996 – REVISED FEBRUARY 2009

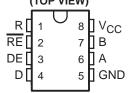
- Integrated Transient Voltage Suppression
- ESD Protection for Bus Terminals Exceeds: ±30 kV IEC 61000-4-2, Contact Discharge ±15 kV IEC 61000-4-2, Air-Gap Discharge ±15 kV EIA/JEDEC Human Body Model
- Circuit Damage Protection of 400-W Peak (Typical) Per IEC 61000-4-5
- Controlled Driver Output-Voltage Slew Rates Allow Longer Cable Stub Lengths
- 250-kbps in Electrically Noisy Environments
- Open-Circuit Fail-Safe Receiver Design
- 1/4 Unit Load Allows for 128 Devices Connected on Bus
- Thermal Shutdown Protection
- Power-Up/-Down Glitch Protection
- Each Transceiver Meets or Exceeds the Requirements of TIA/EIA-485 (RS-485) and ISO/IEC 8482:1993(E) Standards
- Low Disabled Supply Current 300 μA Max
- Pin Compatible With SN75176
- Applications:
  - Industrial Networks
  - Utility Meters
  - Motor Control

#### description

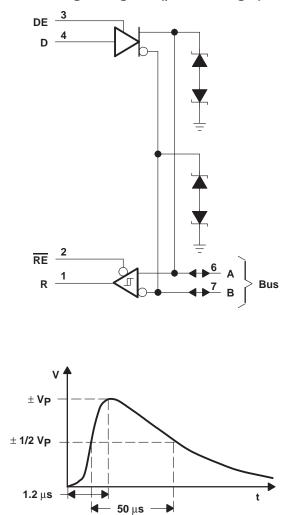
The SN75LBC184 and SN65LBC184 are differential data line transceivers in the trade-standard footprint of the SN75176 with built-in protection against high-energy noise transients. This feature provides a substantial increase in reliability for better immunity to noise transients coupled to the data cable over most existing devices. Use of these circuits provides a reliable low-cost direct-coupled (with no isolation transformer) data line interface without requiring any external components.

The SN75LBC184 and SN65LBC184 can withstand overvoltage transients of 400-W peak (typical). The conventional combination wave called out in IEC 61000-4-5 simulates the overvoltage transient and models a unidirectional surge caused by overvoltages from switching and secondary lightning transients.





functional logic diagram (positive logic)







Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



Copyright © 2009, Texas Instruments Incorporated

#### SN65LBC184, SN75LBC184 DIFFERENTIAL TRANSCEIVER VOLTAGE SUPPRESSION WITH TRAN

SLLS236G - OCTOBER 1996 - REVISED FEBRUARY 2009

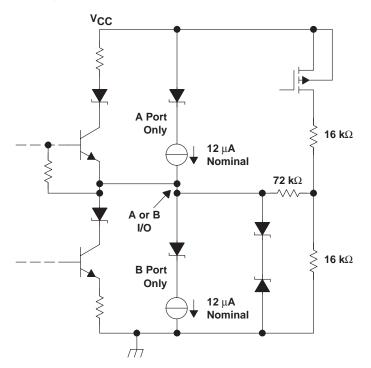
### description (continued)

A biexponential function defined by separate rise and fall times for voltage and current simulates the combination wave. The standard 1.2 µs/50 µs combination waveform is shown in Figure 1 and in the test description in Figure 15.

The device also includes additional desirable features for party-line data buses in electrically noisy environment applications including industrial process control. The differential-driver design incorporates slew-rate-controlled outputs sufficient to transmit data up to 250 kbps. Slew-rate control allows longer unterminated cable runs and longer stub lengths from the main backbone than possible with uncontrolled and faster voltage transitions. A unique receiver design provides a fail-safe output of a high level when the inputs are left floating (open circuit). The SN75LBC184 and SN65LBC184 receiver also includes a high input resistance equivalent to one-fourth unit load allowing connection of up to 128 similar devices on the bus.

The SN75LBC184 is characterized for operation from 0°C to 70°C. The SN65LBC184 is characterized from -40°C to 85°C.

#### schematic of inputs and outputs





# SN65LBC184, SN75LBC184 DIFFERENTIAL TRANSCEIVER WITH TRANSIENT VOLTAGE SUPPRESSION SLLS236G - OCTOBER 1996 - REVISED FEBRUARY 2009

BRIVERT ON OTION TABLE										
INPUT	ENABLE	OUTPUTS								
D	DE	Α	В							
Н	Н	Н	L							
L	Н	L	Н							
Х	L	Z	Z							

### DRIVER FUNCTION TABLE

H = high level, L = low level, ? = indeterminate, X = irrelevant, Z = high impedance (off)

#### **RECEIVER FUNCTION TABLE**

DIFFERENTIAL INPUTS	ENABLE	OUTPUT
A – B	RE	R
$V_{ID} \ge 0.2 V$	L	Н
$-0.2 \text{ V} < \text{V}_{\text{ID}} < 0.2 \text{ V}$	L	?
$V_{ID} \le -0.2 V$	L	L
Х	Н	Z
Open	L	Н

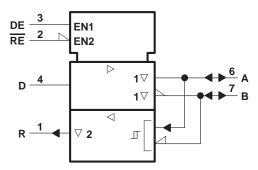
H = high level, L = low level, ? = indeterminate, X = irrelevant, Z = high impedance (off)

#### **AVAILABLE OPTIONS**

		PACKAGE
TA	PLASTIC SMALL-OUTLINE <sup>†</sup> (JEDEC MS-012)	PLASTIC DUAL-IN-LINE PACKAGE (JEDEC MS-001)
0°C to 70°C	SN75LBC184D	SN75LBC184P
-40°C to 85°C	SN65LBC184D	SN65LBC184P

<sup>†</sup>Add R suffix for taped and reel.

## logic symbol<sup>†</sup>



<sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



SLLS236G – OCTOBER 1996 – REVISED FEBRUARY 2009

### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage, V <sub>CC</sub> (see Note 1) Continuous voltage range at any bus terminal Data input/output voltage Receiver output current, I <sub>O</sub> Electrostatic discharge: Contact discharge (IEC61000-4-2) Air discharge (IEC61000-4-2) Human body model (see Note 3)	2) A, B, GND (see Note 2) A, B, GND (see Note 2) A, B, GND (see Note 2)	15 V to 15 V 0.3 V to 7 V ±20 mA ±30 kV ±15 kV ±15 kV
, , , , , , , , , , , , , , , , , , ,	All pins	
All terminals (Class 3A) (see Note All terminals (Class 3B) (see Note	e 2)	±8 kV
Electrical Fast Transient/Burst (IEC 61000–4–4) Continuous total power dissipation (see Note 4)	Á, B, GND	±4 kV

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values, except differential input/output bus voltage, are with respect to network ground terminal.

 GND and bus terminal ESD protection is beyond readily available test equipment capabilities for IEC 61000-4-2, EIA/JEDEC test method A114-A and MIL-STD-883C method 3015. Ratings listed are limits of test equipment; device performance exceeds these limits.

- 3. Tested in accordance with JEDEC Standard 22, Test Method A114-A and IEC 60749-26.
- 4. The driver shuts down at a junction temperature of approximately 160°C. To operate below this temperature, see the Dissipation Rating Table.

DISSIPATION RATING TABLE											
PACKAGE	T <sub>A</sub> ≤ 25°C POWER RATING	DERATING FACTOR ABOVE T <sub>A</sub> = 25°C	T <sub>A</sub> = 70°C POWER RATING	T <sub>A</sub> = 85°C POWER RATING							
D	725 mW	5.8 mW/°C	464 mW	377 mW							
Р	1150 mW	9.2 mW/°C	736 mW	598 mW							

#### recommended operating conditions

		Ν	nin‡	TYP	MAX	UNIT			
Supply voltage, V <sub>CC</sub>			4.75	5	5.25	V			
Voltage at any bus terminal (separatel	y or common mode), VI or VIC		-7		12	V			
High-level input voltage, V <sub>IH</sub>	D, DE, and RE		2			V			
Low-level input voltage, VIL	D, DE, and RE				0.8	V			
Differential input voltage,  VID					12	V			
1 Park law of a drive a summary 1	Driver		-60			mA			
High-level output current, IOH	Receiver		-8	1.75    5    5.25      -7    12      2    0.8      12    12      -60    -60      -8    60      4    0    70	mA				
	Driver				60				
Low-level output current, IOL	Receiver				5 5.25 12 0.8 12 12 60 4 70	mA			
On exercise of the exercise of	SN75LBC184		0		70	°C			
Operating free-air temperature, $T_A$	SN65LBC184		-40		85	°C			

<sup>‡</sup>The algebraic convention, in which the less-positive (more-negative) limit is designated minimum, is used in this data sheet.



# SN65LBC184, SN75LBC184 **DIFFERENTIAL TRANSCEIVER** WITH TRANSIENT VOLTAGE SUPPRESSION SLLS236G – OCTOBER 1996 – REVISED FEBRUARY 2009

## **DRIVER SECTION**

### electrical characteristics over recommended operating conditions (unless otherwise noted)

	PARAMETER	ALTERNATE SYMBOLS	TEST CONDITIONS	MIN	түр†	MAX	UNIT	
			$DE = \overline{RE} = 5 V$ , No Load		12	25	mA	
ICC	Supply current	NA	DE = 0 V, RE = 5 V, No Load		175	300	μΑ	
Iн	High-level input current (D, DE, RE)	NA	V <sub>I</sub> = 2.4 V			50	μA	
ΙL	Low-level input current (D, DE, $\overline{RE}$ )	NA	V <sub>I</sub> = 0.4 V	-50			μΑ	
IOS			$V_{O} = -7 V$	-250	-120			
	Short-circuit output current (see Note 5)	NA	VO = VCC			250	mA	
			V <sub>O</sub> = 12 V			250		
IOZ	High-impedance output current	NA		See Receiver I		mA		
VO	Output voltage	V <sub>oa</sub> , V <sub>ob</sub>	IO = 0	0		VCC	V	
V <sub>OC</sub> (PP)	Peak-to-peak change in common- mode output voltage during state transitions	NA	See Figures 5 and 6	0.8			V	
V <sub>OC</sub>	Common-mode output voltage	V <sub>os</sub>	See Figure 4	1		3	V	
∆VOC(SS)	Magnitude of change, common- mode steady-state output voltage	$ V_{OS} - \overline{V}_{OS} $	See Figure 5			0.1	V	
N/1	Magnitude of differential output		IO = 0	1.5		6	V	
IVODI	voltage  V <sub>A</sub> – V <sub>B</sub>	Vo	$R_L = 54 \Omega$ , See Figure 4	1.5			V	
$\Delta  V_{OD} $	Change in differential voltage mag- nitude between logic states	$   \vee_t   -   \overline{\vee}_t   $	$R_L = 54 \Omega$			0.1	V	

<sup>†</sup> All typical values are measured with  $T_A = 25^{\circ}C$  and  $V_{CC} = 5$  V.

NOTE 5: This parameter is measured with only one output being driven at a time.

### switching characteristics over recommended operating conditions (unless otherwise noted)

	PARAMETER	TEST CO	ONDITIONS	MIN	TYP	MAX	UNIT
<sup>t</sup> d(DH)	Differential output delay time, low-to-high-level output					1.3	μs
<sup>t</sup> d(DL)	Differential-output delay time, high-to-low-level output					1.3	μs
<sup>t</sup> PLH	Propagation delay time, low-to-high-level output		C <sub>L</sub> = 50 pF,		0.5	1.3	μs
<sup>t</sup> PHL	Propagation delay time, high-to-low-level output	$R_L = 54 \Omega,$ See Figure 5			0.5	1.3	μs
<sup>t</sup> sk(p)	Pulse skew ( t <sub>d(DH)</sub> - t <sub>d(DL)</sub>  )	See Figure 3			75	150	ns
t <sub>r</sub>	Rise time, single ended			0.25		1.2	μs
t <sub>f</sub>	Fall time, single ended			0.25		1.2	μs
<sup>t</sup> PZH	Output enable time to high level	R <sub>L</sub> = 110 Ω,	See Figure 2			3.5	μs
t <sub>PZL</sub>	Output enable time to low level	R <sub>L</sub> = 110 Ω,	See Figure 3			3.5	μs
<sup>t</sup> PHZ	Output disable time from high level	R <sub>L</sub> = 110 Ω,	See Figure 2			2	μs
<sup>t</sup> PLZ	Output disable time from low level	R <sub>L</sub> = 110 Ω,	See Figure 3			2	μs



SLLS236G - OCTOBER 1996 - REVISED FEBRUARY 2009

## **RECEIVER SECTION**

## electrical characteristics over recommended operating conditions (unless otherwise noted)

	PARAMETER	TEST	TEST CONDITIONS					UNIT
		DE = RE = 0 V,	No Load				3.9	mA
ICC	Supply current (total package)	RE = 5 V, No Load	DE = 0 V,				300	μΑ
			V <sub>I</sub> = 12 V				250	
	Input current		V <sub>I</sub> = 12 V,	$V^{CC} = 0$			250	μΑ
1		Other input = 0 V	$V_{I} = -7 V$		-200			
			$V_{I} = -7 V$ ,	$\Lambda$ CC = 0	-200			
loz	High-impedance-state output current	$V_{O} = 0.4 \text{ V to } 2.4 \text{ V}$					±100	μA
V <sub>hys</sub>	Input hysteresis voltage					70		mV
$V_{IT+}$	Positive-going input threshold voltage						200	mV
VIT-	Negative-going input threshold voltage				-200			mV
Vон	High-level output voltage	$I_{OH} = -8 \text{ mA}$	Figure 7		2.8			V
VOL	Low-level output voltage	$I_{OL} = 4 \text{ mA}$	Figure 7				0.4	V

<sup>†</sup> All typical values are at  $V_{CC}$  = 5 V,  $T_A$  = 25°C.

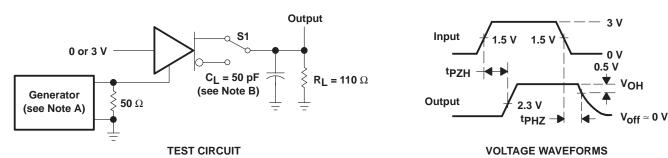
## switching characteristics over recommended operating conditions (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
<sup>t</sup> PLH	Propagation delay time, low-to-high-level output	0.50.5			150	ns
<sup>t</sup> PHL	Propagation delay time, high-to-low-level output	$C_L = 50 \text{ pF},$ See Figure 7			150	ns
<sup>t</sup> sk(p)	Pulse skew ( t <sub>pHL</sub> – t <sub>pLH</sub>  )				50	ns
tr	Rise time, single ended	One Firmer 7		20		ns
t <sub>f</sub>	Fall time, single ended	See Figure 7		20		ns
<sup>t</sup> PZH	Output enable time to high level				100	ns
<sup>t</sup> PZL	Output enable time to low level				100	ns
<sup>t</sup> PHZ	Output disable time from high level	See Figure 8			100	ns
<sup>t</sup> PLZ	Output disable time from low level				100	ns



SLLS236G - OCTOBER 1996 - REVISED FEBRUARY 2009

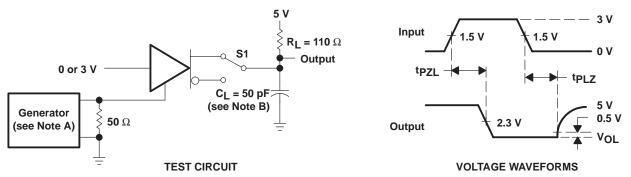
## PARAMETER MEASUREMENT INFORMATION



NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR = 1.25 kHz, 50% duty cycle, t<sub>r</sub>  $\leq$  10 ns, t<sub>f</sub>  $\leq$  10 ns, Z<sub>O</sub> = 50  $\Omega$ .

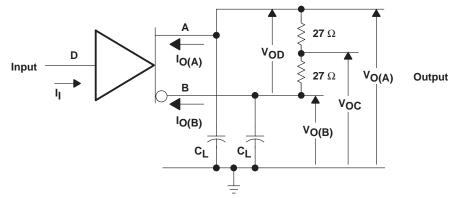
B. CL includes probe and jig capacitance.

#### Figure 2. Driver tPZH and tPHZ Test Circuit and Voltage Waveforms



- NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR = 1.25 kHz, 50% duty cycle, t<sub>r</sub>  $\leq$  10 ns, t<sub>f</sub>  $\leq$  10 ns, Z<sub>O</sub> = 50  $\Omega$ .
  - B. CL includes probe and jig capacitance.

#### Figure 3. Driver tPZL and tPLZ Test Circuit and Voltage Waveforms



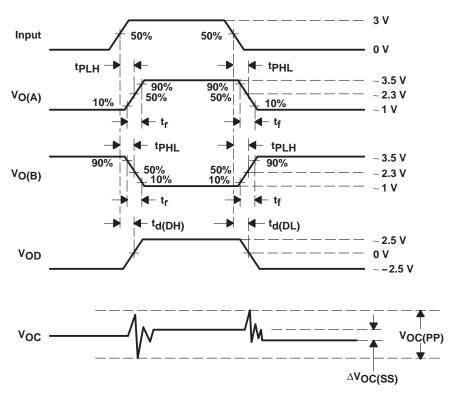
NOTES: A. Resistance values are in ohms and are 1% tolerance.

B. CL includes probe and jig capacitance.

#### Figure 4. Driver Test Circuit, Voltage, and Current Definitions



SLLS236G – OCTOBER 1996 – REVISED FEBRUARY 2009



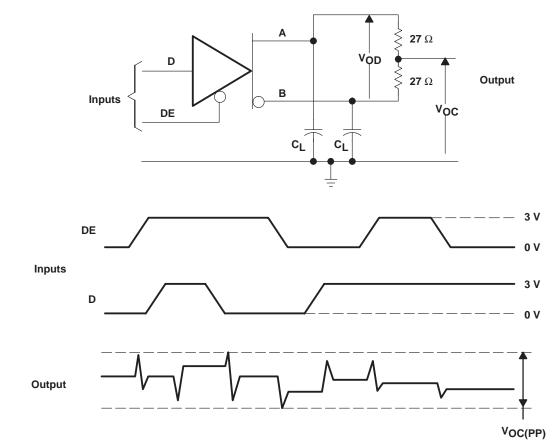
### PARAMETER MEASUREMENT INFORMATION

Figure 5. Driver Timing, Voltage and Current Waveforms



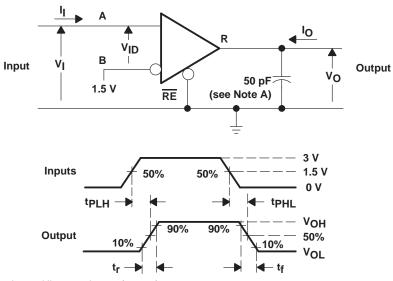
SLLS236G - OCTOBER 1996 - REVISED FEBRUARY 2009

### PARAMETER MEASUREMENT INFORMATION



NOTES: A. Resistance values are in ohms and are 1% tolerance. B.  $C_1$  includes probe and jig capacitance (± 10%).





NOTE A: This value includes probe and jig capacitance ( $\pm$  10%).

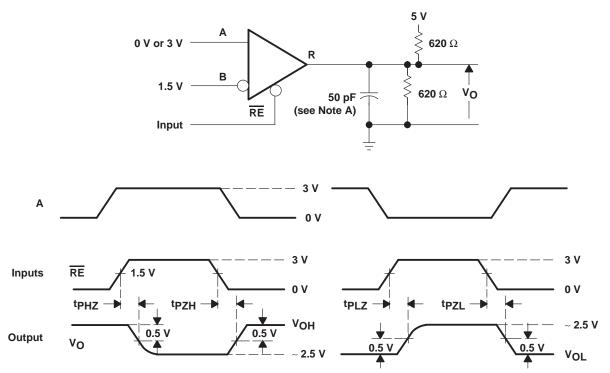
Figure 7. Receiver  $t_{PLH}$  and  $t_{PHL}$  Test Circuit and Voltage Waveforms



#### SN65LBC184, SN75LBC184 **DIFFERENTIAL TRANSCEIVER VOLTAGE SUPPRESSION** W 'H TRANSIENT

SLLS236G - OCTOBER 1996 - REVISED FEBRUARY 2009

### PARAMETER MEASUREMENT INFORMATION



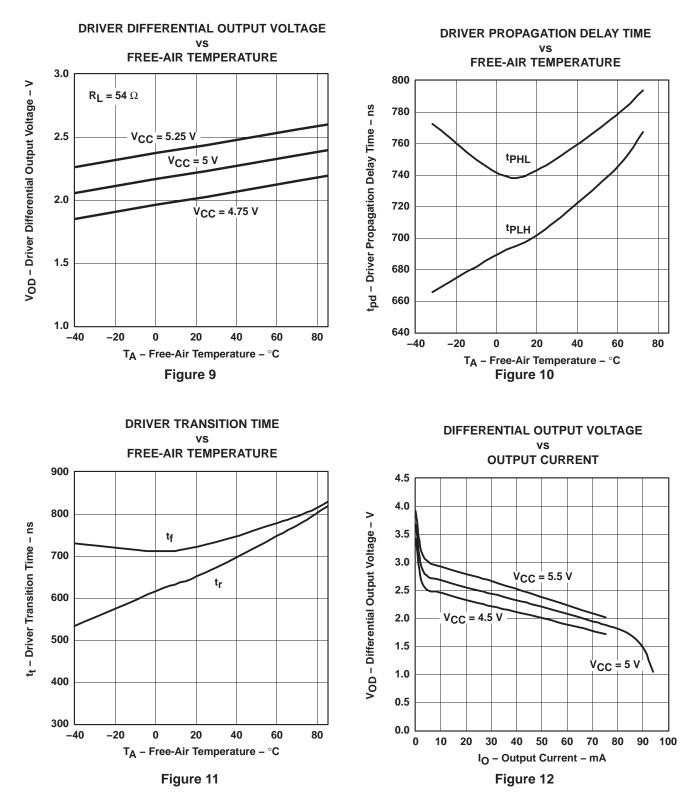
NOTE A: This value includes probe and jig capacitance ( $\pm$  10%).

Figure 8. Receiver  $t_{PZL}$ ,  $t_{PLZ}$ ,  $t_{PZH}$ , and  $t_{PHZ}$  Test Circuit and Voltage Waveforms



SLLS236G - OCTOBER 1996 - REVISED FEBRUARY 2009

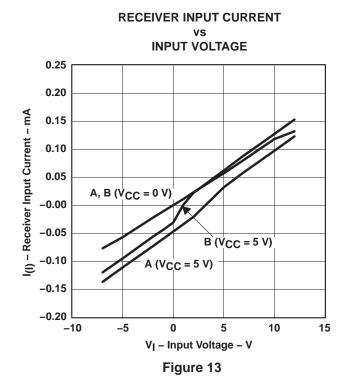




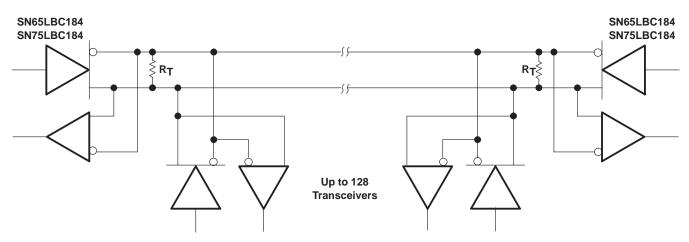


SLLS236G - OCTOBER 1996 - REVISED FEBRUARY 2009

## **TYPICAL CHARACTERISTICS**



#### **APPLICATION INFORMATION**



NOTE A: The line should be terminated at both ends in its characteristic impedance (RT = ZO). Stub lengths off the main line should be kept as short as possible.

Figure 14. Typical Application Circuit



## APPLICATION INFORMATION

### 'LBC184 test description

The 'LBC184 is tested against the IEC 61000–4–5 recommended transient identified as the combination wave. The combination wave provides a 1.2-/50- $\mu$ s open-circuit voltage waveform and a 8-/20- $\mu$ s short-circuit current waveform shown in Figure 15. The testing is performed with a combination/hybrid pulse generator with an effective output impedance of 2  $\Omega$ . The setup for the overvoltage stress is shown in Figure 16 with all testing performed with power applied to the 'LBC184 circuit.

**NOTE** High voltage transient testing is done on a sampling basis.

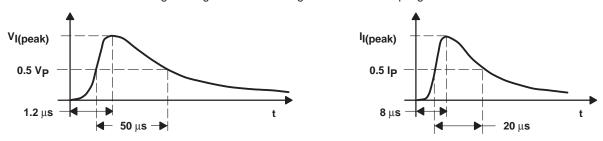
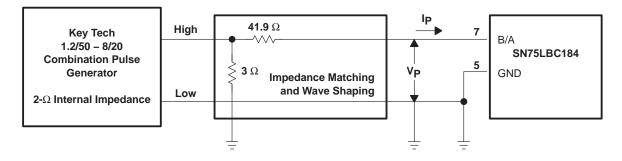


Figure 15. Short-Circuit Current Waveforms

The 'LBC184 is tested and evaluated for both maximum (single pulse) as well as life test (multiple pulse) capabilities. The 'LBC184 is evaluated against transients of both positive and negative polarity and all testing is performed with the worst-case transient polarity. Transient pulses are applied to the bus pins (A & B) across ground as shown in Figure 16.





An example waveform as seen by the 'LBC184 is shown in Figure 17. The bottom trace is current, the middle trace shows the clamping voltage of the device and the top trace is power as calculated from the voltage and current waveforms. This example shows a peak clamping voltage of 33.6 V and peak current of 16 A, thus yielding an absorbed peak power of 538 W.

NOTE

A circuit reset may be required to ensure normal data communications following a transient noise pulse of greater than 250 W peak.



SLLS236G - OCTOBER 1996 - REVISED FEBRUARY 2009

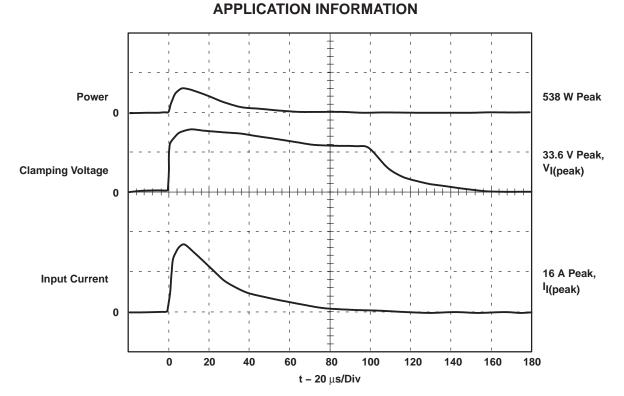


Figure 17. Typical Surge Waveform Measured At Terminals 5 and 7





11-Apr-2013

## PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Top-Side Markings	Samples
SN65LBC184D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	6LB184	Samples
SN65LBC184DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	6LB184	Samples
SN65LBC184DR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	6LB184	Samples
SN65LBC184DRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	6LB184	Samples
SN65LBC184P	ACTIVE	PDIP	Ρ	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	65LBC184	Samples
SN65LBC184PE4	ACTIVE	PDIP	Ρ	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	65LBC184	Samples
SN75LBC184D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	7LB184	Samples
SN75LBC184DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	7LB184	Samples
SN75LBC184DR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	7LB184	Samples
SN75LBC184DRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	7LB184	Samples
SN75LBC184P	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	75LBC184	Samples
SN75LBC184PE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	75LBC184	Samples

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.



#### www.ti.com

## PACKAGE OPTION ADDENDUM

11-Apr-2013

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

## TAPE AND REEL INFORMATION





## QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	-	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN65LBC184DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
SN75LBC184DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1



# PACKAGE MATERIALS INFORMATION

12-Feb-2009



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN65LBC184DR	SOIC	D	8	2500	340.5	338.1	20.6
SN75LBC184DR	SOIC	D	8	2500	340.5	338.1	20.6

P(R-PDIP-T8)

PLASTIC DUAL-IN-LINE PACKAGE



- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001 variation BA.



D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AA.





NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



#### **IMPORTANT NOTICE**

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have *not* been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products		Applications			
Audio	www.ti.com/audio	Automotive and Transportation	www.ti.com/automotive		
Amplifiers	amplifier.ti.com	Communications and Telecom	www.ti.com/communications		
Data Converters	dataconverter.ti.com	Computers and Peripherals	www.ti.com/computers		
DLP® Products	www.dlp.com	Consumer Electronics	www.ti.com/consumer-apps		
DSP	dsp.ti.com	Energy and Lighting	www.ti.com/energy		
Clocks and Timers	www.ti.com/clocks	Industrial	www.ti.com/industrial		
Interface	interface.ti.com	Medical	www.ti.com/medical		
Logic	logic.ti.com	Security	www.ti.com/security		
Power Mgmt	power.ti.com	Space, Avionics and Defense	www.ti.com/space-avionics-defense		
Microcontrollers	microcontroller.ti.com	Video and Imaging	www.ti.com/video		
RFID	www.ti-rfid.com				
OMAP Applications Processors	www.ti.com/omap	TI E2E Community	e2e.ti.com		
Wireless Connectivity	www.ti.com/wirelessconnectivity				

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2014, Texas Instruments Incorporated